10.0 x 3.2 x 0.5 (mm) ISM Ceramic Chip Antenna (AA066)

Engineering Specification

1. Explanation of Product Number

H 2 U 6 4 6 M H L Q 0 2 0 0



2. Features

- *Stable and reliable in performances
- *Low temperature coefficient of frequency
- *Low profile, compact size
- *RoHS 2.0 compliance
- *SMT processes compatible
- *AEC-Q200 compliant

3. Applications

- *ISM Band system.
- *RFID system

4. Description

Unictron's chip antenna series are specially designed for ISM Band applications. Based on Unictron's proprietary design and processes, this chip antenna has excellent stability and sensitivity to consistently provide high signal reception efficiency.

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5. Electrical Specifications (80x40(mm) ground plane)

5-1. Electrical Table:

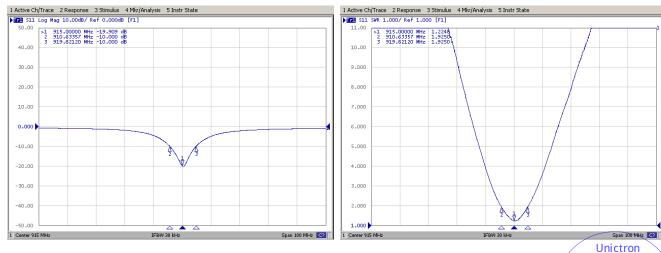
| Characte | eristics | Specifications | Unit |
|--------------------------|-------------|---------------------|------|
| Outline Dimension | S | 10x3.2x0.5 | mm |
| Ground Plane | | 80x40 | mm |
| Working Frequenc | У | 902~928 | MHz |
| VSWR (@ center t | frequency)* | 2 Max. | |
| Characteristic Impedance | | 50 | Ω |
| Polarization | | Linear Polarization | |
| Peak Gain | (@915MHz) | 0.9 (typical**) | dBi |
| Efficiency | | 69 (typical**) | % |

^{*}Center frequency means the frequency with the lowest value in return loss of the chip antenna on the evaluation board..

5-2. Return Loss & VSWR

Return Loss (S₁₁)





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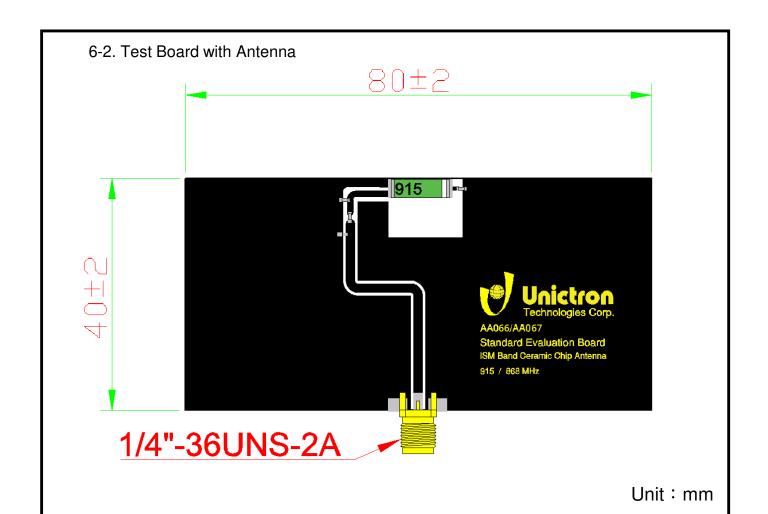
^{**}A typical value is for reference only, not guaranteed.

Antenna Dimensions & Test Board (unit: mm) 6. 6-1. Antenna Dimensions ▲10±0.2 Feed Side Left Vlew Front View Right View NOTE: 1.All materials are RoHS 2.0 compliant. 2." A~©" Critical Dimensions. **Bottom View** 3."()" Reference Dimensions. **PIN Definitions** PIN1 915 PIN2 PIN₁ Top View **Bottom View** PIN 1 2 Soldering PAD Unictron Signal Tuning / Ground hnologies Corp. 2021-12-21 THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF UNICTRON TECHNOLOGIES 詠業科技股份有限公司 CORPORATION AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR Unictron Technologies Corporation SALE OF APPARATUS OR DEVICES WITHOUT **PERMISSION** Website:www.unictron.com Prepared by :Betty Designed by: Ken Checked by : Mike Approved by : Herbert TITLE: 10.0 x 3.2 x 0.5 (mm) ISM Ceramic Chip **DOCUMENT** REV.

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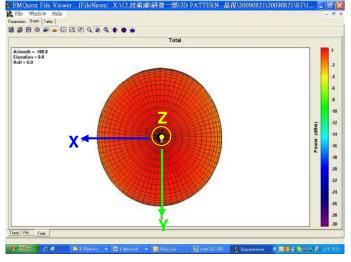
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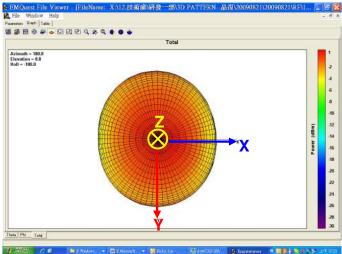
REV.

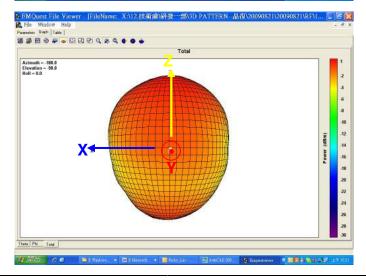
PAGE 4 **OF** 10

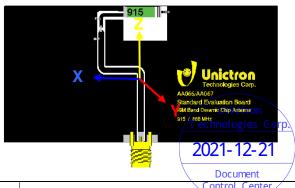
7. Radiation Pattern (80x40(mm) ground plane)

7-1. 3D Gain Pattern (Radiation Pattern at 915 MHz)











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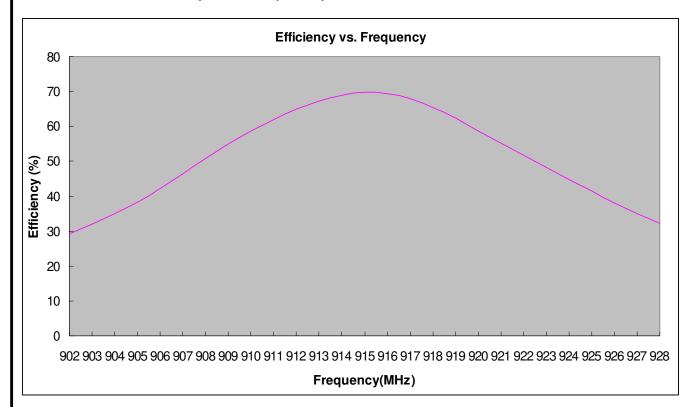
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| Frequency(MHz) | 902 | 903 | 904 | 905 | 906 | 907 | 908 | 909 | 910 | 911 | 912 | 913 | 914 | 915 |
|-----------------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|
| Efficiency (dB) | -5.33 | -4.96 | -4.57 | -4.17 | -3.74 | -3.33 | -2.95 | -2.61 | -2.31 | -2.08 | -1.87 | -1.73 | -1.62 | -1.56 |
| Efficiency (%) | 29.29 | 31.93 | 34.91 | 38.31 | 42.22 | 46.45 | 50.71 | 54.87 | 58.73 | 61.95 | 65.04 | 67.18 | 68.94 | 69.78 |
| Gain (dBi) | -2.75 | -2.35 | -2 | -1.62 | -1.2 | -0.77 | -0.4 | -0.07 | 0.21 | 0.43 | 0.63 | 0.77 | 0.87 | 0.92 |

| Frequency(MHz) | 916 | 917 | 918 | 919 | 920 | 921 | 922 | 923 | 924 | 925 | 926 | 927 | 928 |
|-----------------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|
| Efficiency (dB) | -1.59 | -1.68 | -1.84 | -2.06 | -2.31 | -2.58 | -2.86 | -3.16 | -3.48 | -3.82 | -4.19 | -4.56 | -4.92 |
| Efficiency (%) | 69.33 | 67.94 | 65.48 | 62.29 | 58.73 | 55.18 | 51.79 | 48.33 | 44.85 | 41.5 | 38.08 | 34.98 | 32.21 |
| Gain (dBi) | 0.88 | 0.79 | 0.62 | 0.4 | 0.12 | -0.16 | -0.46 | -0.75 | -1.11 | -1.46 | -1.84 | -2.24 | -2.57 |

7-3. 3D Efficiency vs. Frequency



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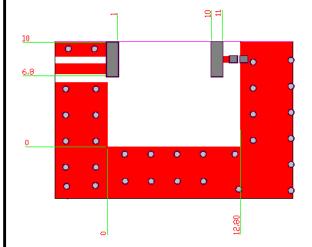
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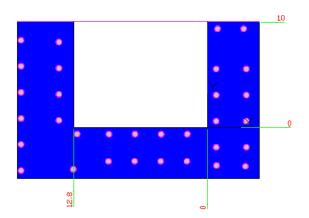
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8. Layout Guide:

a. Solder Land Pattern:

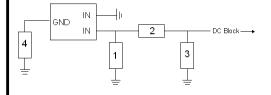
Land pattern for soldering (black marking areas) is as shown below. Matching circuit is needed for good performance, when customer's device is different.





b. Matching circuit:

(Center frequency is about 915 MHz @ 80 x 40 mm² Evaluation Board)



| System Matching Circuit Component | | | | | | |
|-----------------------------------|------------------------------|---------------|----------|--|--|--|
| Location | Description Vendor Tolerance | | | | | |
| 1 | N/ A* | - | - | | | |
| 2 | 0Ω* | (0402) | - | | | |
| 3 | 5.0pF* | Murata (0402) | ±0.05 pF | | | |
| 4 | 10pF* | Murata (0402) | ±5 % | | | |

^{*}Typical reference values which may need to be changed when circuit boards or part vendors are different.

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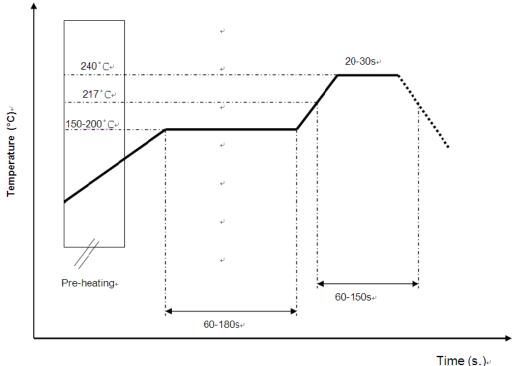
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9. Soldering Conditions:

a. Typical Soldering Profile for Lead-free Process



Time (s.)

10. Reminders for users of Unictron's chip antennas

- a. Since Unictron's chip antennas are made of ceramic materials which show different rigidity than circuit board materials, bending of circuit board at the locations where chip antennas are mounted may cause the cracking of solder joints or antenna itself.
- b. Any connecting strip which will be cut off at PCB assembly process shall be located away from the installation site of chip antenna. Punching of the connecting strip may cause severe bending of the circuit board and cracking of solder joint or chip antenna itself may occur.
- c. Be cautious when ultrasonic welding process needs to be used near the locations where chip antennas are installed. Strong ultrasonic vibration may cause the cracking of chip antenna solder joints.

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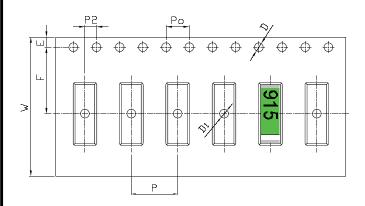
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^{*}Recommended solder paste alloy: SAC305 (Sn96.5 /Ag3 /Cu0.5) Lead Free solder paste

11. Packing:

- (1) Quantity/Reel: 6000pcs/Reel
- (2) Plastic tape:
- a. Tape Drawing



b. Tape Dimensions (unit: mm)

| Feature | Specifications | Tolerances |
|---------|----------------|---------------|
| W | 24.00 | ±0.30 |
| Р | 8.00 | ±0.10 |
| Ш | 1.75 | ±0.10 |
| F | 11.50 | ±0.10 |
| P2 | 2.00 | ±0.10 |
| D | 1.50 | +0.10 0.00 |
| D1 | 1.50 | ±0.10 |
| Ро | 4.00 | ±0.10 |
| 10Po | 40.00 | ±0.20 |

12. Operating & Storage Conditions

12-1. Operating

- (1) Maximum Input Power: 2 W
- (2) Operating Temperature: -40°C to 85°C
- (3) Relative Humidity: 10% to 70%

12-2. Storage (sealed)

- (1) Storage Temperature: -5°C to 40°C
- (2) Relative Humidity: 20% to 70%
- (3) Shelf Life: 1 year

12-3. Storage (unsealed)

Meet the criteria of J-STD-033 MSL2a

12-4. Storage (After mounted on customer's PCB with SMT process)

- (1) Storage Temperature: -40°C to 85°C
- (2) Relative Humidity: 10% to 70%

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13. Notice

(1) Installation Guide:

Please refer to Unictron's application note "General guidelines for the installation of Unictron's chip antennas" for further information.

(2) All specifications are subject to change without notice.

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